

Amendments to the specification

Please amend the title of the application as follows:

-- ~~PRINTED CIRCUIT BOARD~~ MANUFACTURING METHOD OF AND
PRINTED CIRCUIT BOARD --

Please amend the abstract of the application as follows:

-- ~~The present invention provides a method of manufacturing printed a circuit board capable of formation of via holes having a low aspect ratio and formation of fine lines, and a printed circuit board manufactured by the method. The method of manufacturing a printed circuit board 10 according to the present invention includes a step of selectively forming a plating layer 16 for lands 22a and 22b on a metal foil 14 on the printed circuit board 10, a step of adjusting the thickness of the plating layer 16, and a step of forming the metal foil 14 into lines 14a. The aspect ratio of via holes 28 formed on lands 22a and 22b can be adjusted by adjusting the thickness of the lands 22a and 22b.~~

The present invention provides a method of manufacturing a printed circuit board. The method includes the steps of preparing an insulating substrate having a front surface and a back surface and a layer of metal foil formed on each of the front surface and the back surface; selectively forming a plating layer for forming a land on at least one of the metal foils; adjusting a thickness of the plating layer; and forming the metal foils into lines. --